

# HITACHI SEMICONDUCTOR TECHNICAL UPDATE

DATE	5th July, 1999	No.	TN-SH7-171 A/E
THEME	HD6417750BP200 usage notice of reflow and storage conditions.		
CLASSIFICATION	<input type="checkbox"/> Spec. change <input checked="" type="checkbox"/> Limitation on Use <input checked="" type="checkbox"/> Supplement of Documents		
PRODUCT NAME	HD6417750BP200		
REFERENCE DOCUMENTS	SH4(SH7750) Hardware manual	Effective Date	eternity
		From	

HD6417750BP200 have followed usage notice for reflow and storage conditions.

Although this product is supplied in a moisture resistant packaged condition, be sure to follow the conditions below when the package is heated to a high temperature using a method such as vapor phase reflow or repair. If not, package cracks or characteristics failure may occur.

(1) Storage time after opening the moisture resistant package for each reflow temperature.

(a) Reflow temperature(235°C max)

Storage time after opening the moisture resistant package, use the LSI within 72hr.

(b) Reflow temperature(225°C max)

Storage time after opening the moisture resistant package, use the LSI within 168hr.

Storage condition

Temperature : Below 30°C

Humidity : Below 60%

(2) If the storage time exceeds "(1)", bake the LSI before soldering it with following conditions.

Baking conditions

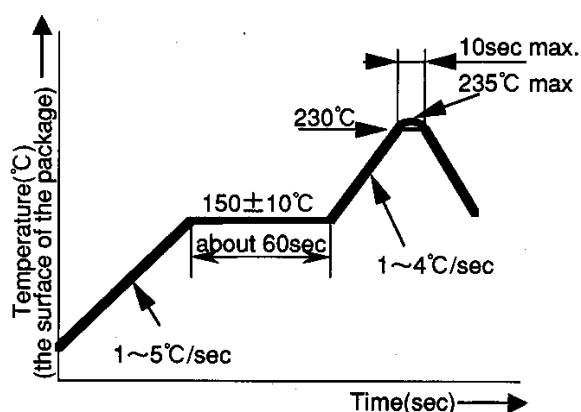
125°C, 16~24hr, Power off

After baking, the time and the storage conditions until soldering are the same as (1).

(3) The recommended temperature at reflow time is shown in below.

The way to solder the LSI is infrared reflow or air reflow, or N2 reflow.

(a) Reflow temperature 235°C max



(b) Reflow temperature 225°C max

